

**REMARKS**

In accordance with the foregoing, claims 1, 3, and 4 have been amended. Claim 2 has been cancelled without prejudice or disclaimer. Accordingly, claims 1 and 3-27 are pending and under consideration.

**Claims 5-10 and 12-27**

In item 5, the Office Action notes that claims 5-10 and 12-27 are in condition for allowance.

**Rejection of Claims 1 and 11 Under 35 U.S.C. §102(b)**

The Office Action rejects claims 1 and 11 under 35 U.S.C. §102(b) as being anticipated by U.S. Patent 5,929,651 issued to Leas et al. (hereinafter referred to as "Leas"). This rejection is respectfully traversed.

In item 4 on page 3, the Office Action notes that Lease does not disclose, "the insert module is partitioned in a plurality of semiconductor device accommodators by a horizontal partition wall and a vertical partition wall."

Applicants respectfully submit that Leas does not disclose, teach, or suggest at least, "wherein the insert module is partitioned into a plurality of semiconductor device accommodators by a horizontal partition wall and a vertical partition wall, and wherein each semiconductor device accommodator is capable of accommodating the semiconductor device within the horizontal partition wall and the vertical partition wall," as recited in claim 1. Therefore, for at least these reasons, claim 1 is patentably distinguishable from the cited reference.

Claim 11 depends from claim 1 and includes all of the features of claim 1. Therefore, for at least these reasons, claim 11 is patentably distinguishable from the cited reference.

Accordingly, withdrawal of this rejection is respectfully requested.

**Rejection of Claim 2-4 Under 35 U.S.C. §103(a)**

The Office Action rejects claims 2-4 under 35 U.S.C. §103(a) as being unpatentable over Leas in view of U.S. Patent 6,720,784 issued to Martter et al. (hereinafter referred to as "Martter"). This rejection is respectfully traversed.

Leas and Martter, taken separately or in combination, do not disclose, teach, or suggest at least, "wherein the insert module is partitioned into a plurality of semiconductor device

accommodators by a horizontal partition wall and a vertical partition wall, and wherein each semiconductor device accommodator is capable of accommodating the semiconductor device within the horizontal partition wall and the vertical partition wall," as recited in claim 1.

In item 4 on page 3, the Office Action asserts, "Martter et al disclose in Figs. 1-2, the insert module (14 of figure 2) is partitioned in a plurality of semiconductor device accommodators (26 of figure 2) by a horizontal partition wall and a vertical partition wall (fig. 2) for holding a plurality of the device under test at the time during test to save time and quickly testing."

However, col. 2, lines 53-54 of Martter discloses, "FIG. 3 is a schematic side view of the burn-in board of FIG. 2." Sockets 26 are mounted to board 10 and connected to circuit 18. However, Figure 3, which is a side view of Figure 2 does not show a horizontal partition wall and does not show a vertical partition wall. Figure 2 also does not show a horizontal partition wall or a vertical partition wall. Because Martter does not disclose a horizontal partition wall and does not disclose a vertical partition wall, Martter does not disclose, "each semiconductor device accommodator is capable of accommodating the semiconductor device within the horizontal partition wall and the vertical partition wall," as recited in claim 1. Therefore, for at least these reasons, claim 1 is patentably distinguishable from the cited references.

Claims 3, 4, and 11 depend from claim 1 and include all of the features of claim 1. Therefore, for at least these reasons, claims 2, 4, and 11 are also patentably distinguishable from the cited references.

Accordingly, withdrawal of this rejection is respectfully requested.

#### Summary

Claims 1 and 3-27 are pending and under consideration. It is respectfully submitted that none of the references taken alone or in combination disclose the present claimed invention.

There being no further outstanding objections or rejections, it is submitted that the application is in condition for allowance. An early action to that effect is courteously solicited

If there are any formal matters remaining after this response, the Examiner is requested to telephone the undersigned to attend to these matters.

Serial No. 10/823,546

If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 19-3935.

Respectfully submitted,

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